

# Product Termination Notification

Product Group: SIL/Fri Jun 18, 2021/PTN-SIL-020-2021-REV-0

## Product Obsolescence - SQJ912AEP

**DESCRIPTION OF CHANGE:** The affected part number listed in this notification has been approved for termination. The recommended replacement part is the SQJ912DEP-T1\_GE3. This device offers a closely matched solution and an upgrade to our 530 SG N-Channel MOSFET technology from the same wafer fab and is assembled in the same facility as the SQJ912AEP-T1\_GE3.

**REASON FOR CHANGE: Standardization of materials** 

EXPECTED INFLUENCE ON QUALITY/RELIABILTY/PERFORMANCE: None

PART NUMBERS/SERIES/FAMILIES AFFECTED: SQJ912AEP-T1\_GE3, SQJ912AEP-T2\_GE3, SQJ912AEP-T1\_BE3,

VISHAY BRAND(s): Vishay Siliconix

#### TIME SCHEDULE:

Last Time Buy Date: Mon Jan 10, 2022 Last Time Ship Date: Fri Jul 15, 2022

SAMPLE AVAILABILITY: Qualified samples of replacement product are available immediately

PRODUCT IDENTIFICATION: SQJ912DEP-T1\_GE3

QUALIFICATION DATA: AEC Q101 qualification data of replacement product is available. Qualification PPAP is available now.

This PCN is considered approved, without further notification, unless we receive specific customer concerns before Mon Jan 10, 2022 or as specified by contract.

ISSUED BY: Lance Gurrola, business-americas@vishay.com

For further information, please contact your regional Vishay office.

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		Affected Part Number AEC Q101 Qualified	SQJ912AEP Yes ProverPAK SQ-81						Replacement Part Number AEC Q101 Qualified	SQJ912DEP Yes ProverPAK SQ-91						
		Process Technolomy	200M cells /in <sup>2</sup>						Process Technology	520M cells /in <sup>2</sup>						
		100% Rg & UIS Tested	Yes						100% Rg and UIS Tested	Yes						
		Datasheet Rev	A						Datasheet Rev	A						
												1				
Absolute Mavium Datings	Combol	Tool Conditions	1 Junit	Units				Cumhad	Test Conditions	Linuit	Units				Tune of Change	Bish
Drain-Source Voltage	VDS	Test Conditions	40	v				VDS	Test conditions	40	v				None	None
Gate-Source Voltage	VGS		+20	v				VGS		+20	v				None	None
Continuous Drain Current	ID	TC = 25°C	30	4				ID.	TC = 25*C	30	Δ.				None	None
Continuous Drain Current	ID	TC = 125°C	29	Δ.				ID	TC = 125°C	26	Δ.	1			Lower	None
Continuous Source Current (Diode Conduction)	is		30	A				IS		25	A				Lower	None
Pulsed Drain Current	IDM		120	A				IDM		120	A				None	None
Single Pulse Avalanche Current	IAS		26	Α				IAS		19	A	1			Lower	None unless part exposed to high current over voltage events
Single Pulse Avalanche Energy	EAS	L = 0.1mH	34	mJ				EAS	L = 0.1mH	18	mJ	1			Lower	None unless part exposed to high energy over voltage events
Max Power Dissipation	PD	TC = 25*C	48	w				PD	TC = 25*C	27	W	1			Lower	Very low. Quoted Pd is not a practical value in most designs
Max Power Dissipation	PD	TC = 125°C	16	w				PD	TC = 125°C	9	W	1			Lower	Very low. Quoted Pd is not a practical value in most designs
Opetating Junction	TJ		-55 to +175	°C				TJ		-55 to +175	°C				None	None
Thermal Resistance J_A	RthJA	PCB Mount	85	*C/W				RthJA	PCB Mount	85	*C/W				None	None
Thermal Resistance J-C	RthJC		3.1	*C/W				RthJC		5.5	*C/W				Higher	Low. Lower Rds(on) will compensate
						_										
Specifications TJ=25°C unless otherwise noted		Test Co	anditions	MIN	ТҮР	мах	Units		Test Cor	ditions	MIN	TYP	MAX	Units	Type of Change	Risk
Drain-Source Breakdown Voltage	VDS	VGS=0V,	ID=250uA	40			v	VDS	VGS=0V, I	D=250uA	40			v	None	None
Gate-Source Threshold Voltage	VGS(th)	VDS=VGS, ID=250uA		1.5	2	2.5	v	VGS(th)	VDS=VGS,	ID=250uA	1.5	2	2.5	v	None	None
Gate -Source Leakage	IGSS	VDS=0V, VGS=±20V				±100	nA	IGSS	VDS=0V, V	VDS=0V, VGS=±20V			±100	nA	None	None
		VGS=0V	VDS=40V			1	uA		VGS=0V	VDS=60V			1	uА	None	None
Zero Voltage Drain Current	IDSS	VGS=0V	VDS=40V, Tj=125*C			50	uA	IDSS	VGS=0V	VDS=60V, Tj=125*C			50	uА	None	None
		VGS=0V	VDS=40V, Tj=175*C			150	uA		VGS=0V	VDS=60V, Tj=125*C			150	uА	None	None
On-State Drain Current	ID(ON)	VGS=10V	VDS25V	30			A	ID(ON)	VGS=10V	VDS≥-5V	15			A	None	None
Drain-Source On-State Resistance	RDS(on)	VGS=10V	ID=9.7A		0.0077	0.0093	Ω		VGS=10V	ID=-8A		0.0059	0.0073	Ω	Lower	None
		VGS=10V	ID=9.7A, Tj=125*C			0.0138	Ω	RDS(op)	VGS=10V	ID=7A, Tj=125*C			0.0106	Ω	Lower	None
		VGS=10V	ID=9.7A, Tj=175*C			0.0169	Ω		VGS=10V	ID=7A, Tj=175*C			0.0125	Ω	Lower	None
		VGS=4.5V	ID=8.9A		0.0093	0.0111	Ω		VGS=4.5V	ID=5A		0.0082	0.0102	Ω	Lower	None
Forward Transconductance	gfs	VDS=15	V, ID=10A		58		S	gfs	VDS=15V	, ID=7A		47		S	Lower	None
Input Capacitance	Ciss				1438	1835		Ciss				1246	1745		Lower	None. Values are too close to have an impact. Compare Og
Output Capacitance	Coss	VGS=0V	VDS=20V, f=1MHz		217	271	pF	Coss	VGS=0V	VDS=25V, f=1MHz		346	483	pF	Higher	None. Non-linear characteristic. No overall impact.
Reverse Transfer Capacitance	Crss				91	114		Crss				31	44		Lower	None. Non-linear characteristic. No overall impact. Compare Qgd
Total Gate Charge	Qg				25.6	38		Qg				24	36		Lower	None
Gate-Source Charge	Qgs	VGS=10V	VDS=20V, ID=11.3A		4		nC	Qgs	VGS=10V	VDS=-20V, ID=11.3A		5		nC	Higher	None
Gate-Drain Charge	Ogd				4			Qgd				5			Higher	None
Gate Resistance	Rg	f=1	MHz	0.72	1.44	2.2	Ω	Rg	f=1M	1Hz	1.4	2.8	4.2	Ω	Higher	Very low. Switching speeds are very similar with 10ns impact on tf
Turn-On Delay Time	td(on)	1			10 15		td(on)				10	20		Higher	None. Switching speeds are not impacted	
Rise Time	tr	1			9	14	1	tr	<b>1</b>			4	10		Lower	None. Switching speeds are not impacted
Turn-Off Delay Time	td(off)	VDD=20V, RL=20Ω, ID=1A, Vgen=10V, Rg=1Ω			23	35	ns td(	td(off)	VDD=20V, RL=201, ID=1A, Vgen=10V, Rg=11			25	50	ns	Higher	None. Switching speeds are not impacted
Fall Time	tf				11	17	1	tf				21	35		Higher	Very low, 10ns impact will not affect applications < 500kHz
Pulsed Source-Drain Current	ISM					120	Α	ISM					120	A	None	None
Forward Voltage	VSD	If=6.5A VGS=0V			0.8	1.1	v	VSD	Is=7A V	GS=0V		0.79	1.2	v	Changed	None
Body diode reverse recovery time	trr	I <sub>s</sub> =6.5A, di/dt=100A/us					ns	trr				25	50	ns	Additional data	Not on previous data sheet
Body diode reverse recovery charge	Qrr						nC	Qrr	1.=44 di/d	-1004/ur		16	32	nC	Additional data	Not on previous data sheet
Reverse recovery fall time	ta						ns	ta	. <sub>г</sub> ни, шуш			11		ns	Additional data	Not on previous data sheet
Reverse recovery rise time	tb						ns	tb				14		ns	Additional data	Not on previous data sheet
Body diode peak reverse recovery current	I <sub>RM(REC)</sub>						А	I <sub>RM(REC)</sub>				-1.1		А	Additional data	Not on previous data sheet